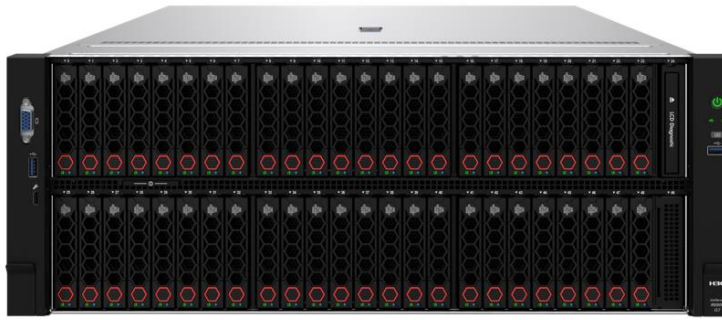




H3C UniServer R6900 G7 Server

High-Scalability Enterprise-Class Quad-Socket Rack Server for Mission-Critical Applications



Extraordinary performance

- 4 Intel® Xeon® 6th generation scalable processors
- 64 DIMMs DDR5 6400
- 6 DW or 12 SW GPU cards

Excellent scalability and flexibility

- Symmetric Dual-Layer motherboard design
- Supports up to 58 drives for flexible combinations
- Supports up to 25 I/O expansion slots

Enhanced Security design

- TCM/TPM trusted computing module
- Trusted silicon root firmware security system
- Secure decommissioning function

Product Overview

H3C UniServer R6900 G7 is a new-generation enterprise-class 4U quad-socket rack server independently developed by H3C for mission-critical applications. The overall system continues H3C's design philosophy of high efficiency, agility, security, reliability, low carbon, and energy saving for mission-critical servers. Leveraging the all-new Intel Xeon processor platform, it has undergone a comprehensive and magnificent upgrade, achieving overall improvements in computing efficiency, expansion capability, security, and so on. It is an ideal option for data-intensive applications such as large-scale virtualization, database, memory computing, data analysis, data warehouse, business intelligence, and ERP.

Product features

Efficient, Reliable, and Low-Carbon Combined

H3C UniServer R6900 G7 uses the latest Intel®Xeon® 6th processor computing platform, delivering up to 344 physical cores for the overall system, a 43.3% increase over the previous generation. It supports next-generation DDR5 6400MT/s memory and CXL2.0 memory expansion, combined with support for up to 6 double-width enterprise-class accelerator cards, bringing astonishingly powerful computing performance to the data center.

Under the high load operation of data-intensive services, heat dissipation is a critical factor affecting stable server operation. With the support of its symmetric dual-layer motherboard design, R6900 G7 achieves stable and efficient heat dissipation for CPUs, memory, drives, and IO cards, ensuring the server remains rock-solid even under extreme conditions.

R6900 G7 provides energy-saving technologies such as CPU intelligent dynamic energy saving, fan AI tuning, and power mode intelligent adjustment. While meeting business requirements, it effectively reduces server power consumption, contributing to building a green, low-carbon data center for enterprise customers.

Intelligent-Ready Full Life Cycle Management (LCM)

H3C UniSystem unified management platform can cover all stages of the server, from deployment, operation and maintenance, diagnosis to decommissioning. The high-speed out-of-band (OOB) operating system installation patented technology and agile stateless computing function can improve service deployment and mobility efficiency by 10 times; The newly evolved application optimization template can intelligently identify service loads, match the best configuration, and thereby improve overall system performance by 5%; With the support of AI technology, the H3C server Intelligent Management Platform can bring customers a convenient and efficient operation and maintenance management experience.

Technical specifications

CPU	4 6th Generation Intel®Xeon® processor series 86 Cores for each Processor with 350W power consumption
Memory	64 DDR5 RDIMM Slots, 6400 MT/s Data Rate
RAID controller	Optional Mezz SATA RAID controller (CTL), supporting RAID 0/1/10/5 Optional standard PCIe slot based HBA cards and RAID controllers
FBWC	8 GB Cache Supports Supercapacitor protection
Storage	Supports SAS/SATA HDD/SSD drives; maximum support for front 50SFF + rear 8LFF Supports up to 48 front U.2 NVMe drives*; supports PCIe NVMe storage accelerator cards Optional dual M.2/SD cards as startup disks; M.2 supports types including NVMe or SATA
Network	1 onboard dedicated 1Gbps management network port Optional expansion via OCP 3.0 x16 slots for 4x1GE copper ports or 2x10GE copper/fiber ports or 2x25GE fiber ports Optional standard PCIe slot-based network adapters; supports 1/10/25/40/100/200/400Gb NICs or IB cards
Expansion slots	Up to 22 PCIe 5.0 standard form factor slots 2 OCP 3.0 slots, supporting hot swapping 1 Mezz slot, PCIe 5.0 standard
Ports	2 VGA Rear Ports (1 Front, 1 Rear) 3 USB 3.0 Ports (1 Front, 2 Rear), 3 USB 2.0 Ports (1 Front, 2 Internal) 1 Management Port , 1 serial port
GPU	Up to 6 double-width or 12 single-width GPU cards
Optical drive	External Optical Disk Drive, Optional
Management	Unified management platform, providing HDM agentless management tool (with dedicated management port) and H3C iFIST/UniSystem management software Optional LCD touchable intelligent management module
Security	Intelligent Front Security Bezel TCM/TPM2.0 Silicon Root of Trust Two-Factor Authentication Secure decommissioning function
Power supplies	Optional up to 4 power supplies, optional Platinum/Titanium level, supporting N+N redundancy Optional 336V DC power supply with N+N redundancy Supports 8 N+1 hot-swappable redundant fans
Standards	CE, UL , FCC, VCCI, CB, etc.

Operating temperature	5°C to 45° C (41°F to 113°F) (Operating temperature support varies depending on different configurations. For details, please refer to the detailed product technical documentation description.)
Dimensions (H×W×D)	4U Height Without a security bezel: 174.8×447×830mm (6.88×17.60×32.68 in) With a security bezel: 174.8×447×858mm (6.88×17.60×33.78 in)

- *The options may be different depending on the specific requirement. Restrictions and limitations may apply. To confirm availability, refer to related user guide or visit H3C website <https://www.h3c.com/en/home/htb/>.



New H3C Technologies Co., Limited
Beijing Headquarters
Tower 1, LSH Center, 8 Guangshun South Street, Chaoyang District, Beijing, China
Zip: 100102
Hangzhou Headquarters
No.466 Changhe Road, Binjiang District, Hangzhou, Zhejiang, China
Zip: 310052
Tel: +86-571-86760000
Fax: +86-571-86760001

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